



News Release



Left to Right: C.H. Ang, Bill Haberlin (SiGe COO), S.W. Chan (SiGe Director of Operations), C.S. Ho



Unisem Receives 2009 Best Packaging Supplier Award from SiGe

Kuala Lumpur, 19 May, 2010 – Unisem recently the Best Packaging of the Year Award from SiGe for 2009. This award was in recognition of excellent service last year by Unisem's Ipoh factory.

Presenting the award to Unisem on behalf of SiGe was their COO, Bill Haberlin and their Director of Operations, S.W. Chan. Receiving the award on behalf of Unisem was Group COO, C.H. Ang and the Ipoh factory's COO, C.S. Ho.

SiGe Semiconductor designs and delivers innovative radio frequency (RF) solutions for next-generation wireless applications including voice, data, and video. SiGe is the market-leading supplier of RF front end solutions and modules that allow today's top consumer equipment manufacturers to provide high-performance WiFi links in their products.